

TENTATIVE

TOSHIBA GATE TURN-OFF THYRISTOR

**SG3000JX26G**

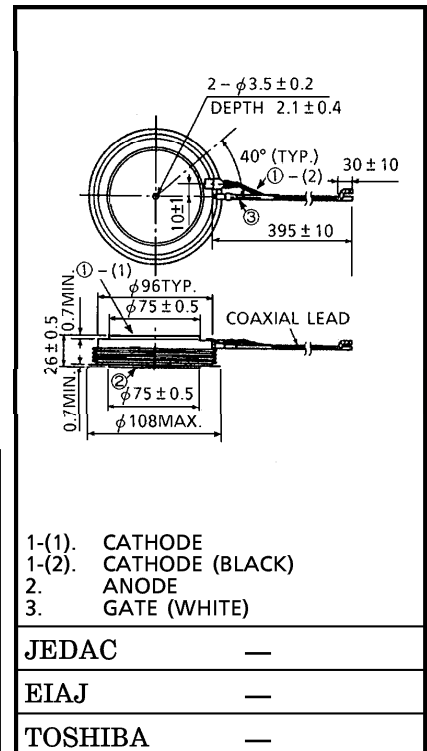
INVERTER APPLICATION

Unit in mm

- Repetitive Peak Off-State Voltage :  $V_{DRM} = 6000\text{ V}$   
(Note 1)
- Repetitive Peak Reverse Voltage :  $V_{RRM} = 17\text{ V}$
- R.M.S On-State Current :  $I_T(\text{RMS}) = 1200\text{ A}$
- Peak Turn-Off Current :  $I_{TGQM} = 3000\text{ A}$
- Critical Rate of Rise of On-State Current :  $di/dt = 400\text{ A}/\mu\text{s}$
- Critical Rate of Rise of Off-State Voltage :  $dv/dt = 1000\text{ V}/\mu\text{s}$

## MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Off-State Voltage (Note 1)	$V_{DRM}$	6000	V
Repetitive Peak Reverse Voltage	$V_{RRM}$	17	V
Peak Turn-Off Current (Note 2)	$I_{TGQM}$	3000	A
R.M.S On-State Current (Note 3)	$I_T(\text{RMS})$	1200	A
Peak One Cycle Surge On-State Current (Non Repetitive, 10 ms-Width Half Sine Waveform)	$I_{TSM}$	16000	A
Critical Rate of Rise of On-State Current (Note 4)	$di/dt$	400	A/ $\mu\text{s}$
Peak Forward Gate Current	$I_{FGM}$	100	A
Average Gate Power Dissipation	$P_G(\text{AV})$	150	W
R.M.S Gate Current (Note 5)	$I_G(\text{RMS})$	42	A
Peak Reverse Gate Voltage (At Static)	$V_{RGM}$	17	V
Operation Junction Temperature Range	$T_j$	-40~125	°C
Storage Temperature Range	$T_{stg}$	-40~150	°C
Mounting Force	—	$33.3 \pm 4.9$	kN



Weight : 1290 g

(Note 1) :  $V_{GK} = -2\text{ V}$ (Note 2) :  $V_D = 3000\text{ V}$ ,  $V_{DM} \leq 5000\text{ V}$ ,  $C_S \geq 3\text{ }\mu\text{F}$ ,  $di_{GQ}/dt \geq 40\text{ A}/\mu\text{s}$ ,  $V_{DSP} \leq 1000\text{ V}$ ,  
 $L_S \leq 0.2\text{ }\mu\text{H}$ 

(Note 3) : 50 Hz Half Sine Waveform

(Note 4) :  $V_D \leq 4000\text{ V}$ ,  $I_{TM} \leq 3000\text{ A}$ ,  $I_G \geq 35\text{ A}$  ( $t_r \leq 1\text{ }\mu\text{s}$ ),  $f \leq 50\text{ Hz}$ ,  $C_S \leq 6\text{ }\mu\text{F}$ ,  
 $R_S \geq 5\text{ }\Omega$ ,  $25^\circ\text{C} \leq T_j \leq 125^\circ\text{C}$ 

(Note 5) : Ambient Temperature of coaxial gate-cathode lead = 90°C

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## ELECTRICAL CHARACTERISTICS

CHARACTERISTICS	SYMBOL	TEST CONDITION		MIN	TYP.	MAX	UNIT
Repetitive Peak Off-State Current	I <sub>DRM</sub>	V <sub>DRM</sub> = 6000 V, V <sub>GK</sub> = −2 V T <sub>j</sub> = 125°C		—	—	200	mA
Repetitive Peak Reverse Current	I <sub>RRM</sub>	V <sub>RRM</sub> = 17 V T <sub>j</sub> = 125°C		—	—	10	mA
Repetitive Peak Reverse Gate Current	I <sub>RGM</sub>	V <sub>RGM</sub> = 17 V T <sub>j</sub> = 125°C		—	—	10	mA
Peak On-State Voltage	V <sub>TM</sub>	I <sub>TM</sub> = 3000 A, T <sub>j</sub> = 125°C		—	—	4.3	V
Gate Trigger Voltage	V <sub>GT</sub>	V <sub>D</sub> = 24 V R <sub>L</sub> = 0.1 Ω	T <sub>j</sub> = −40°C	—	—	2.5	V
			T <sub>j</sub> = 25°C	—	—	1.5	V
Gate Trigger Current	I <sub>GT</sub>		T <sub>j</sub> = −40°C	—	—	—	A
			T <sub>j</sub> = 25°C	—	—	3.5	A
Turn-On Delay Time	t <sub>d</sub>	V <sub>D</sub> = 3000 V, I <sub>TM</sub> = 3000 A di / dt = 400 A / μs		—	—	3.0	μs
Turn-On Time	t <sub>gt</sub>	I <sub>GM</sub> = 35 A (t <sub>r</sub> = 1 μs) T <sub>j</sub> = 25°C, non-snubber		—	—	10	μs
Critical Rate of Rise of Off-State Voltage	dv / dt	V <sub>DRM</sub> = 3000 V T <sub>j</sub> = 125°C, V <sub>GK</sub> = −5 V Exponential Rise		1350	—	—	V / μs
Storage Time	t <sub>s</sub>	I <sub>TGQ</sub> = 3000 A		—	—	30	μs
Gate Turn-Off Time	t <sub>gq</sub>	V <sub>DM</sub> = 5000 V, T <sub>j</sub> = 125°C		—	—	33	μs
Tail Time	t <sub>tail</sub>	V <sub>D</sub> = 3000 V, C <sub>S</sub> = 3 μF di <sub>GQ</sub> / dt = 50 A / μs		—	—	120	μs
Gate Turn-Off Current	I <sub>GQ</sub>	Off squeeze current ≥ 300 mA		—	—	850	A
Thermal Resistance	R <sub>th(j-f)</sub>	Junction to fin		—	—	0.014	°C / W

